

Precautions for component layout

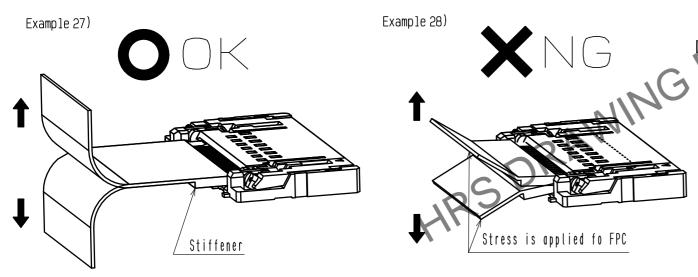
While the FPC is under tension due to the connecting configuration. extra stress may be applied to the connector. As a result, conduction failure may occur due to the extra stress. In order to prevent such kind of conduction failure.

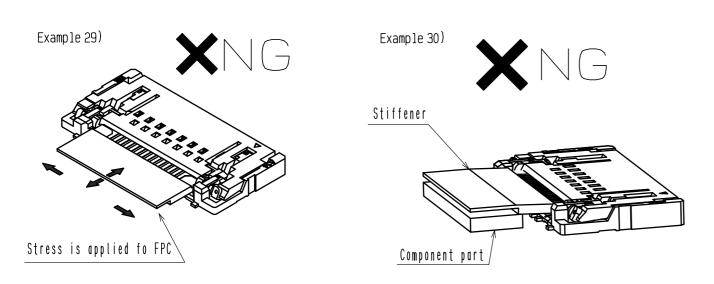
please read through the following parts before making circuits/mechanism design.

[Caution]

Α

- If the FPC/FFC has to be curled/bended in your cabling design. please keep enough degree of freedom in your design to keep the FPC tension free. In this regard the stiffener is parallel to the PCB (Example27).
- Avoid applying forces to/pulling the FPC along/perpendicular to the direction of FPC insertion. Do not bend the FPC excessively near the connector during use. or it may cause contact failure or FPC breakage. Stabilizing the FPC is recommended (Example 28, 29).
- Do not mount other components touching to the FPC underneath the FPC stiffener (Example 30).
- Make adjustments with the FPC manufacturer for FPC bending performance and wire breakage.
- Keep a sufficient FPC insertion space in the stage of the layout in order to avoid incorrect FPC insertion. Appropriate FPC length and component layout are recommended for assembly ease. Too short FPC length makes assembly difficult.
- Keep enough space for the rotation of the actuator during PCB and component layout design.





Instructions for mounting on the PCB

Follow the instructions shown below when mounting on the PCB.

[Caution]

- Refer to recommended layouts on the page 1 for PCB and stencil pattern.
- Using either narrower land pattern or wider stencil pattern than recommendation may end up with excessive amount of solder/flux climbing on contact. Please inspect the size of solder fillet and flux climbing height of the mounted connector while using different land/stencil pattern from our recommendation.
- -Clearance between the mounting surface of the connector contact lead and the bottom of the housing is very small. Solder resist/silk screening applied underneath the connector may interfere with the connector. This may lead to soldering defect/insufficient fillet formation.

Please verify your solder resist/silk screening design carefully before implementing the design.

- Apply reflow temperature profile within the specified conditions. For specific applications, the recommended temperature may vary depending on type/volume/thickness of solder paste and size/thickness of PCB. Please consult with your solder paste and equipment manufacturer for specific recommendations.
- -Please try to minimize the warpage of the PCB. Soldering failure could still occur due to the PCB warpage even if the coplanarity of the connecter is under 0.1mm.
- If the connector is mounting on FPC. please make sure to put a stiffener on the backside of the FPC.

 Recommended stiffner: 61ass epoxy material with thickness of 0.3 mm MIN.

- Do not apply 1 N or greater external force on the connector when unreeling or handling the connector before mounting. Excessive mechanical stress may damage the connector before mounting.

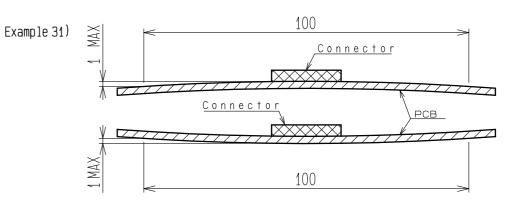
| Instructions for PCB handling after mounting the connector | Follow the instructions shown below when mounting on the PCB.

[Caution]

- ·Splitting a large PCB into several pieces
- ·Installing mounting screw on PCB

During the assembly processes described above, care shall be taken so as not to give any stresses of deflection or twisting to the PCB. Stresses applied on PCB may damage the connector as well

- The warpage of a 100 mm wide PCB should remain within 0.5 mm (example 31) The warpage of PCB may apply excessive stress on the connnector and damage the connector.



<Instruction manual(5)>

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	PART NO.	FH82-14S-0.25SHW	
	CODE NO.	CL0580-5501-0-00	1

[Instructions on manual soldering]

Follow the instructions shown below when soldering the connector manually during repair work, etc.

[Caution]

- Do not perform manual soldering with the FPC inserted into the connector.
- Do not heat the connector excessively. Be very careful not to let the soldering iron contact any parts other than connector leads. Otherwise, the connector may be deformed or melt.
- Do not supply excessive solder (or flux).
- If excessive solder (or flux) is supplied on the contact lead, solder or flux may adhere to the contact point or rotating parts of the actuator, resulting in conduction failure or a rotation failure of the actuator.

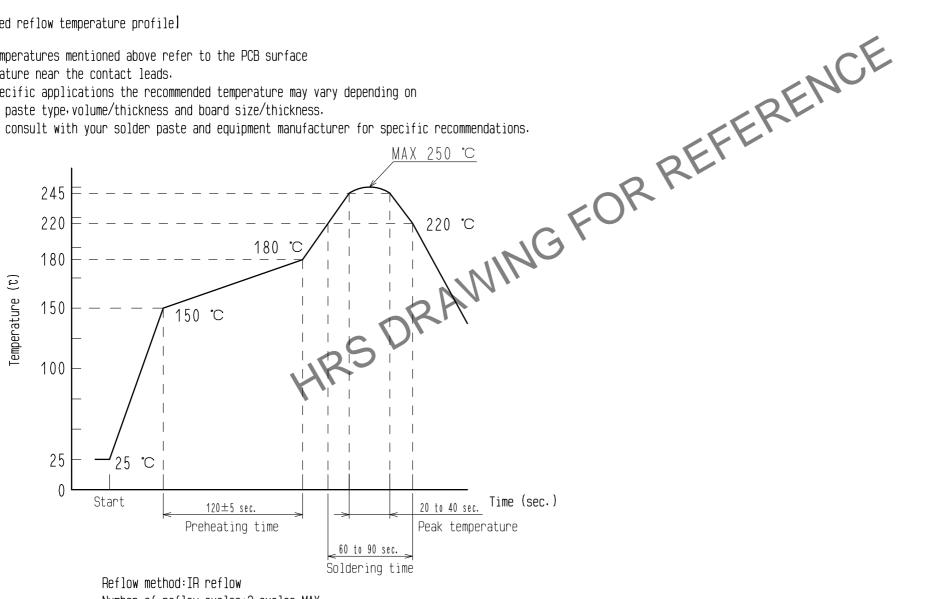
Recommended reflow temperature profile!

The temperatures mentioned above refer to the PCB surface temperature near the contact leads.

For specific applications the recommended temperature may vary depending on

solder paste type, volume/thickness and board size/thickness.

Please consult with your solder paste and equipment manufacturer for specific recommendations.



Number of reflow cycles:2 cycles MAX.

1)Reflow time

Duration above 220°, 60 to 90 sec MAX.

(Peak temperature: 250°, 20 to 40 sec MAX.)

2)Pre-heat time

FORM HC0011-5-8 1

Pre-heat temperature(MIN):150℃

Pre-heat temperature(MAX):180℃

Pre-heat time: 120 \pm 5 sec.

<Recommended reflow temperature profile>

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